

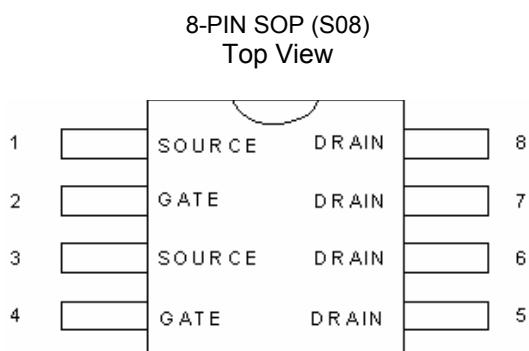
## GENERAL DESCRIPTION

The CMT4953G provide the designer with the best combination of fast switching , ruggedized device design , low on-resistance and cost-effectiveness. The SOP-8 package is universally preferred for all commercial-industrial mount applications and suited for low voltage applications such as DC/DC converters.

## APPLICATIONS

- ◆ Power Management in Notebook
- ◆ Portable Equipment
- ◆ Battery Powered System
- ◆ DC/DC Converter
- ◆ Load Switch
- ◆ DSC
- ◆ LCD Display inverter

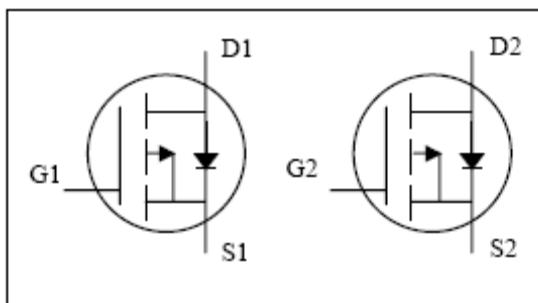
## PIN CONFIGURATION



## FEATURES

- ◆ Advanced Trench Process Technology
- ◆ High Density Cell Design For Ultra Low On-Resistance
- ◆ Fully Characterized Avalanche Voltage and Current
- ◆ Improved Shoot-Through FOM
- ◆ SO-8 Package Design

## SYMBOL



**P-Channel MOSFET**

## ORDERING INFORMATION

Part Number	Package
CMT4953G	SOP-8

\*Note: G : Suffix for Pb Free Product

## ABSOLUTE MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Drain- Source Voltage		V <sub>DS</sub>	-30	V
Gate- Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current <sup>1</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-4.5	A
Pulsed Drain Current <sup>2</sup>		I <sub>DM</sub>	-23	A
Total Power Dissipation <sup>1</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	2	W
Operating Junction Temperature Range		T <sub>J</sub>	-55 to 150	°C
Storage Temperature Range		T <sub>STG</sub>	-55 to 150	°C
Linear Derating Factor			0.02	°C/W
Thermal Resistance Junction-ambient <sup>1</sup> (Max)		R <sub>thj-amb</sub>	62.5	°C/W

## ELECTRICAL CHARACTERISTICS

Unless otherwise specified,  $T_J = 25^\circ\text{C}$ . (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-4.6\text{A}$	-	-	55	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-3.6\text{A}$	-	-	90	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1	-	-2.5	V
$g_{\text{fs}}$	Forward Transconductance <sup>2</sup>	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-4.6\text{A}$	-	5	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current ( $T_J=25^\circ\text{C}$ )	$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm20\text{V}$	-	-	$\pm100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=-4.6\text{A}$	-	11.7	-	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=-15\text{V}$	-	2.1	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=-10\text{V}$	-	2.9	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=-15\text{V}$	-	9	-	ns
$t_r$	Rise Time	$I_{\text{D}}=-1\text{A}$	-	10	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$R_G=6\Omega, V_{\text{GS}}=-10\text{V}$	-	37	-	ns
$t_f$	Fall Time	$R_D=15\Omega$	-	23	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	582	-	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=-15\text{V}$	-	125	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	86	-	pF

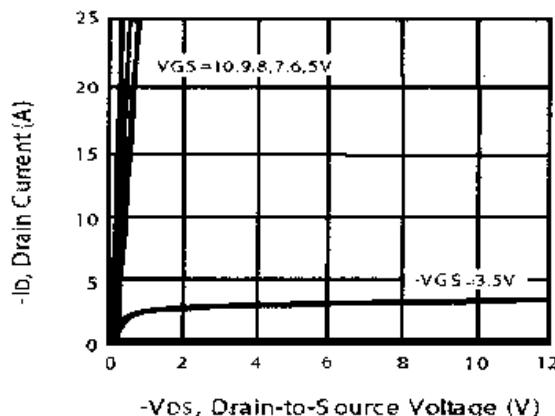
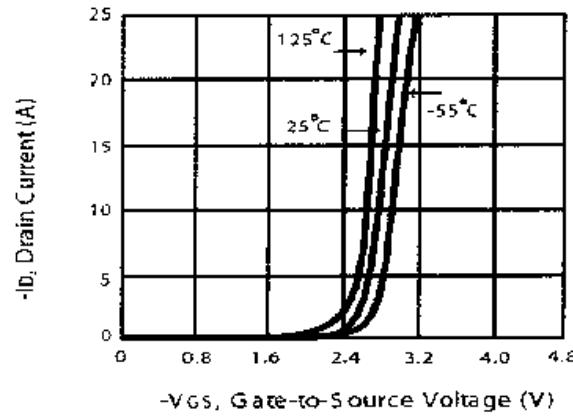
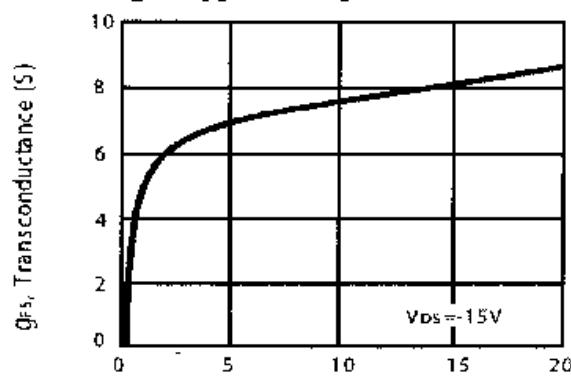
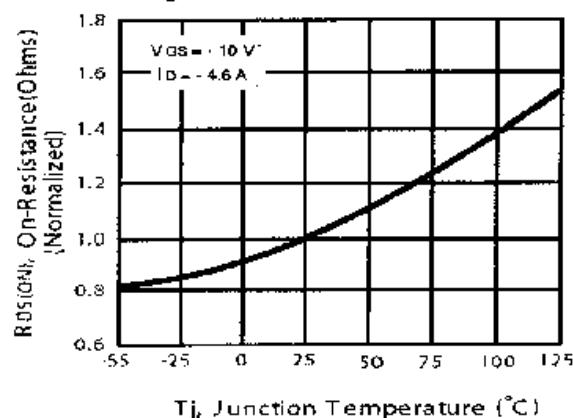
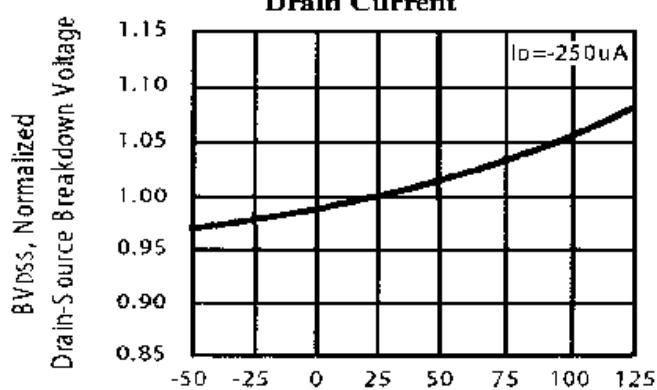
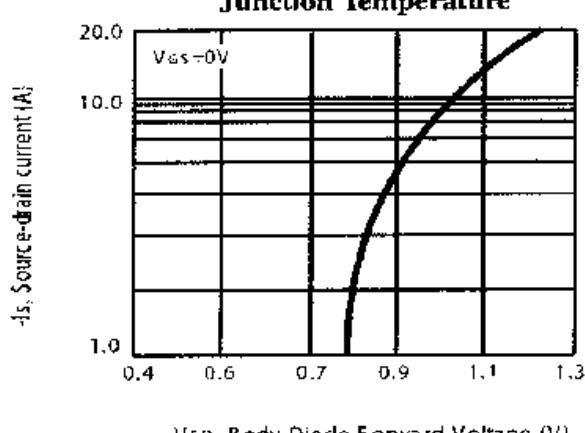
## Source-Drain Diode

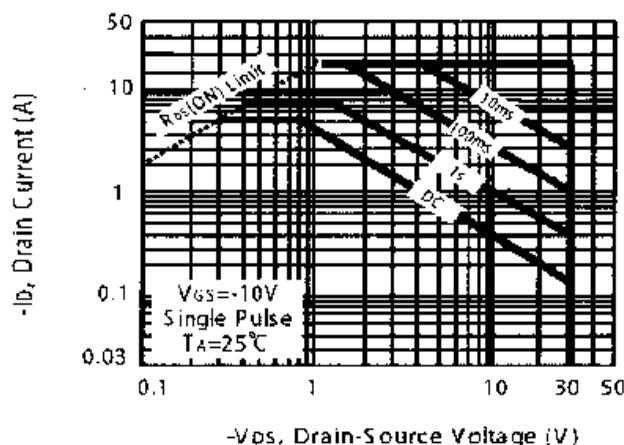
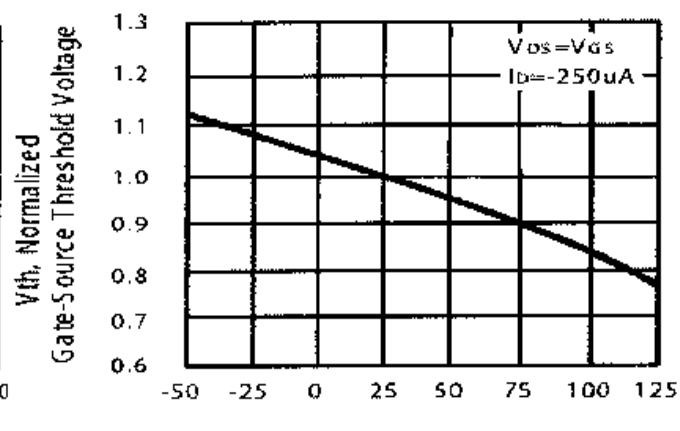
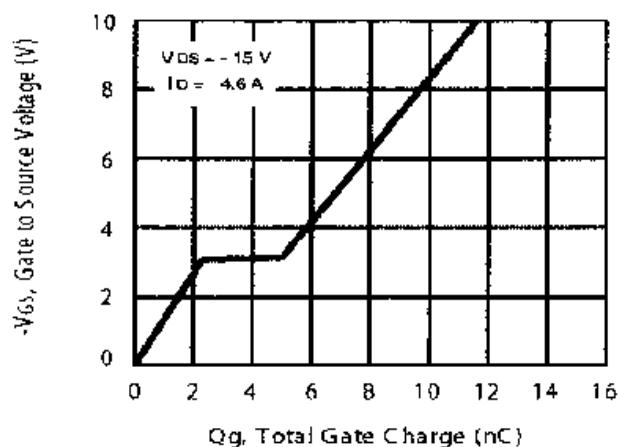
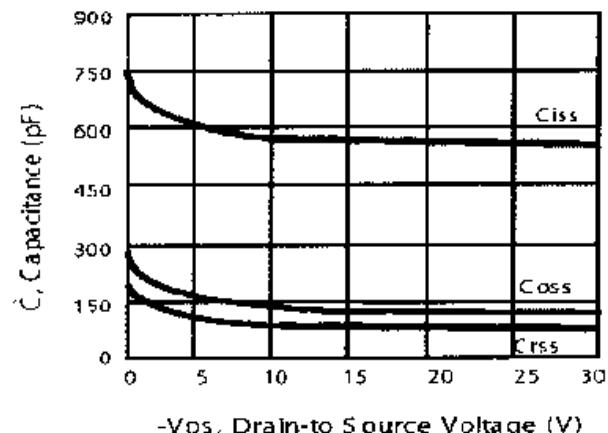
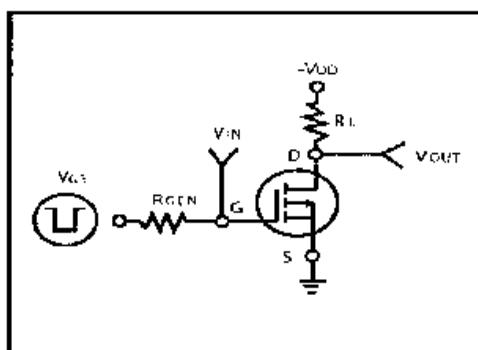
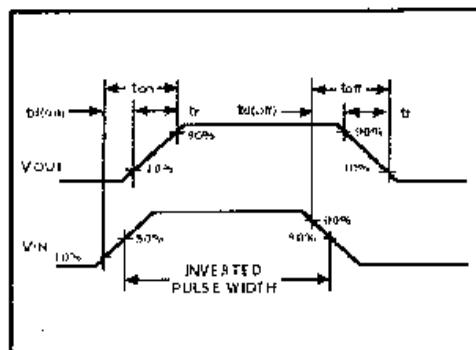
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_S=-1.7\text{A}, V_{\text{GS}}=0\text{V}$	-	-0.84	-1.2	V

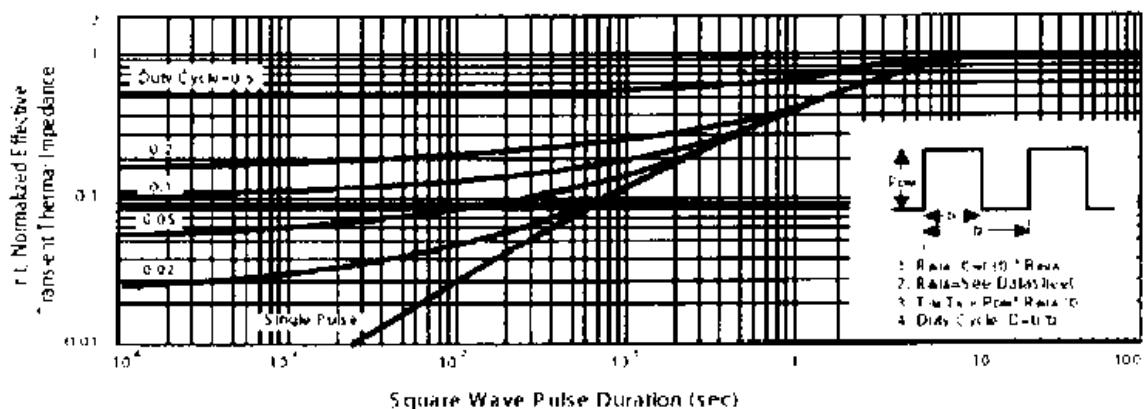
### Notes:

- 1.Surface mounted on FR4 Board ,  $t \leq 2\%$
- 2.Pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .

## TYPICAL CHARACTERISTICS

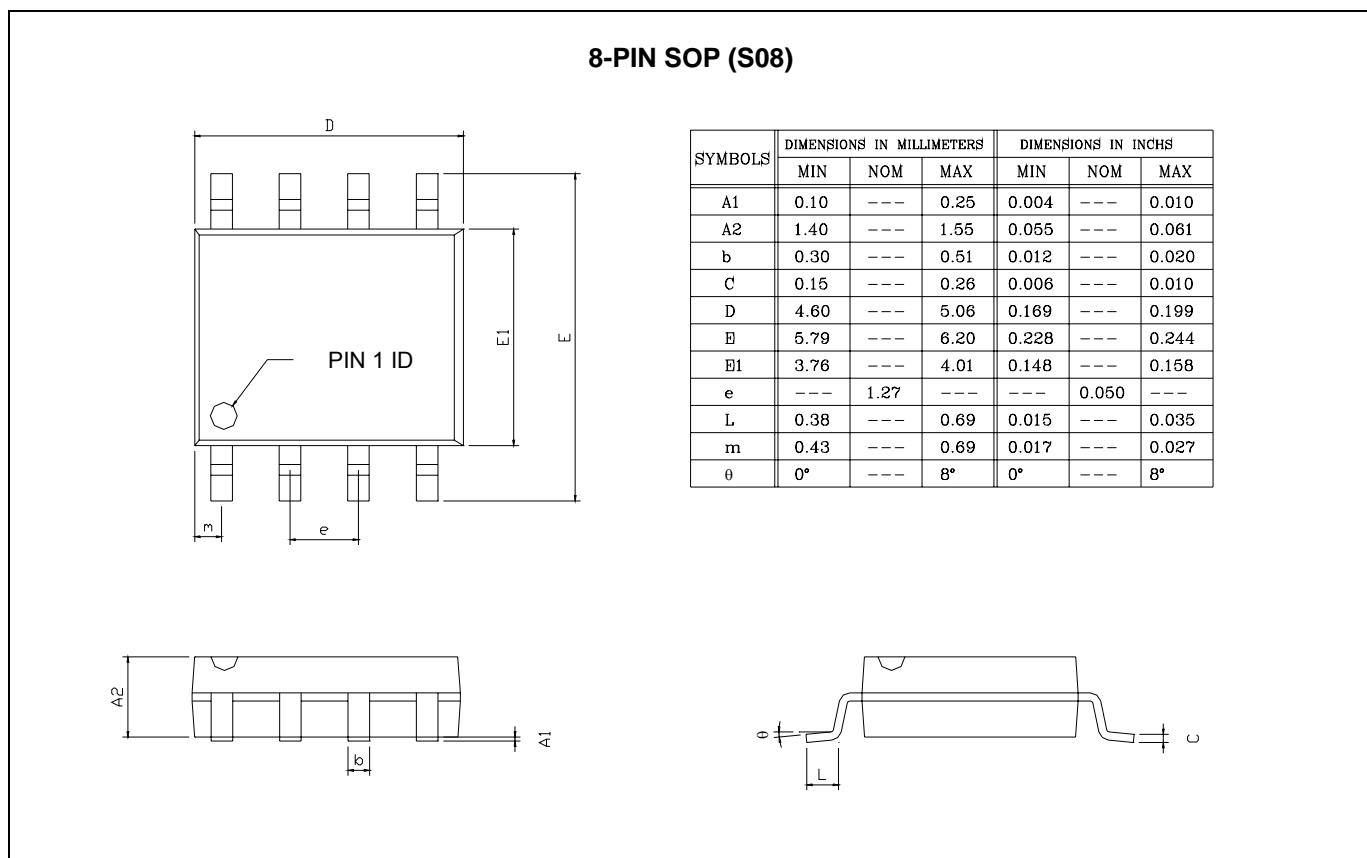
**Characteristics Curve**

**Fig 1. Typical Output Characteristics**

**Fig 2. Transfer Characteristics**

**Fig 3. Transconductance v.s.  
Drain Current**

**Fig 4. On-Resistance v.s.  
Junction Temperature**

**Fig 5. Breakdown Voltage  
v.s. Junction Temperature**

**Fig 6. Body Diode Forward Voltage  
v.s. Source Current**


**Fig 7. Maximum Safe Operating Area**

**Fig 8. Gate Threshold Voltage v.s. Junction Temperature**

**Fig 9. Gate Charge Characteristics**

**Fig 10. Typical Capacitance Characteristics**

**Fig 11. Switching Time Circuit**

**Fig 12. Switching Time Waveform**



**Fig 13. Normalized Thermal Transient Impedance Curve**

## PACKAGE DIMENSION



## IMPORTANT NOTICE

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